





ZXMP6A13F

60V P-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

V _{(BR)DSS}	Max R _{DS(on)}	Max I _D T _A = 25°C		
-60V	400mΩ @ V _{GS} = -10V	-1.1A		
	600mΩ @ V _{GS} = -4.5V	-0.9A		

Description

This MOSFET utilizes a unique structure that combines the benefits of low on-resistance with fast switching speed, making it ideal for high-efficiency power management applications.

Applications

- DC DC converters
- Power management functions
- · Relay and solenoid driving
- Motor control

Features

- · Fast switching speed
- Low input capacitance
- Low gate charge
- Totally Lead-Free & Fully RoHS compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability
- PPAP capable (Note 4)

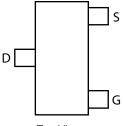
Mechanical Data

- Case: SOT23
- Case Material: Molded Plastic, UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin Plated Leads, Solderable per MIL-STD-202, Method 208 63
- Weight: 0.008 grams (approximate)

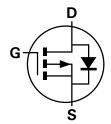
SOT23



Top View



Top View Pin Out



Equivalent Circuit

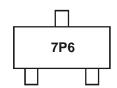
Ordering Information (Notes 4 & 5)

Product	Compliance	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
ZXMP6A13FTA	AEC-Q101	7P6	7	8	3000 Units
ZXMP6A13FQTA	Automotive	7P6	7	8	3000 Units

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- 2. See http://www.diodes.com for more information about Diodes Incorporated's definitions of Halogen and Antimony free, "Green" and Lead-Free.
- 3. Halogen and Antimony free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- Automotive products are AEC-Q101 qualified and are PPAP capable. Automotive, AEC-Q101 and standard products are electrically and thermally the same, except where specified.
- 5. For packaging details, go to our website at http://www.diodes.com

Marking Information



7P6 = Product Type Marking Code



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic				Symbol	Value	Units
Drain-Source Voltage				V_{DSS}	-60	V
Gate-Source Voltage				V_{GS}	±20	V
Continuous Drain Current	V _{GS} = 10V	T _A = 70°C	(Note 7) (Note 7) (Note 6)	l _D	-1.1 -0.8 -0.9	А
Pulsed Drain Current (Note 8)				I _{DM}	-4.0	A
Continuous Source Current (Body Diode) (Note 7)				Is	-1.2	А
Pulsed Source Current (Body Diode) (Note 8)				I _{SM}	-4.0	A

Thermal Characteristics (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 6)	D-	625	mW
Linear Derating Factor	P _D	5	mW/°C
Power Dissipation (Note 7)	В	806	mW
Linear Derating Factor	P _D	6.5	mW/°C
Thermal Resistance, Junction to Ambient (Note 6)	$R_{\theta JA}$	200	°C/W
Thermal Resistance, Junction to Ambient (Note 7)	R _{0JA}	155	°C/W
Thermal Resistance, Junction to Leads (Note 9)	$R_{ heta JL}$	194	°C/W
Operating and Storage Temperature Range	T_{J} , T_{STG}	-55 to +150	°C

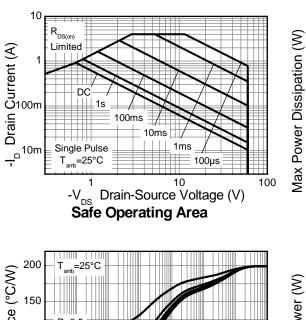
Notes:

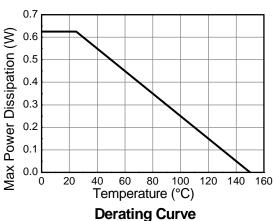
- 6. For a device surface mounted on 25mm x 25mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions
- 7. For a device surface mounted on FR4 PCB measured at t ≤ 5 secs.

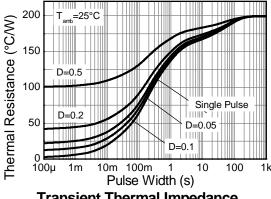
 8. Repetitive rating 25mm x 25mm FR4 PCB, D = 0.05 pulse width = 10µs pulse current limited by maximum junction temperature.
- 9. Thermal resistance from junction to solder-point (at the end of the collector lead).

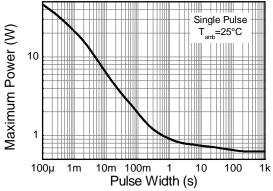


Thermal Characteristics









Transient Thermal Impedance

Pulse Power Dissipation



Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

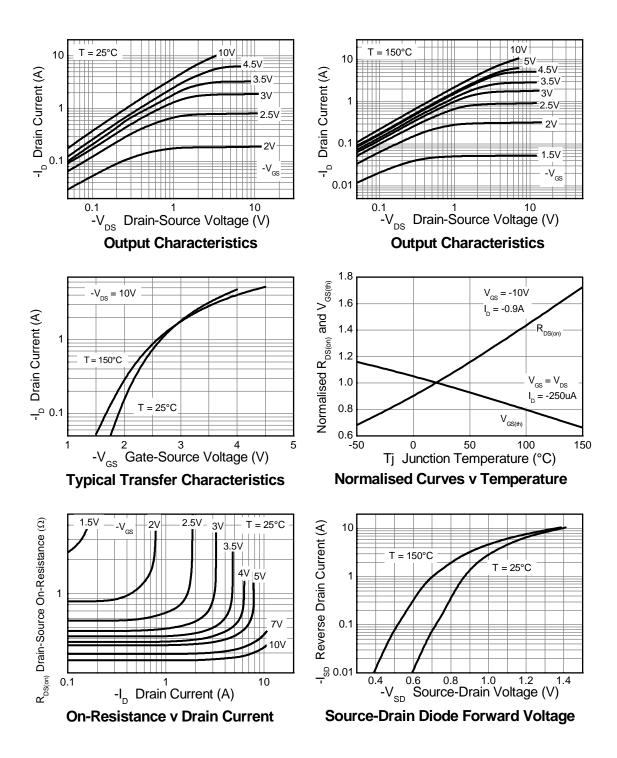
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS							
Drain-Source Breakdown Voltage	BV_{DSS}	-60	_	_	V	$I_D = -250 \mu A, V_{GS} = 0 V$	
Zero Gate Voltage Drain Current	I _{DSS}	_	_	-0.5	μΑ	$V_{DS} = -60V, V_{GS} = 0V$	
Gate-Source Leakage	I _{GSS}	_	_	±100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$	
ON CHARACTERISTICS							
Gate Threshold Voltage	V _{GS(th)}	-1.0	_	-3.0	V	$I_D = -250 \mu A$, $V_{DS} = V_{GS}$	
Static Drain-Source On-Resistance (Note 10)	D (2)			0.400	Ω	$V_{GS} = -10V, I_D = -0.9A$	
Static Drain-Source On-Resistance (Note 10)	R _{DS} (ON)	_		0.600	32	$V_{GS} = -4.5V$, $I_D = -0.8A$	
Forward Transconductance (Notes 10 and 12)	g _{fs}	_	1.8	_	S	$V_{DS} = -15V$, $I_{D} = -0.9A$	
Diode Forward Voltage (Note 10)	V_{SD}	_	-0.85	-0.95	V	$T_J = 25$ °C, $I_S = -0.8$ A, $V_{GS} = 0$ V	
Reverse Recovery Time (Note 12)	t _{rr}	_	21.1	_	ns	$T_J = 25^{\circ}C$, $I_F = -0.9A$,	
Reverse Recovery Charge (Note 12)	Q_{rr}	_	19.3	_	nC	nC di/dt = 100A/μs	
DYNAMIC CHARACTERISTICS (Note 12)							
Input Capacitance	C _{iss}	_	219	_		V _{DS} = -30V, V _{GS} = 0V f = 1.0MHz	
Output Capacitance	Coss	_	25.7	_	pF		
Reverse Transfer Capacitance	C _{rss}	_	20.5	_			
Turn-On Delay Time (Note 11)	t _{D(on)}	_	1.6	_			
Turn-On Rise Time (Note 11)	tr	_	2.2	_		V_{DD} = -30V, I_D = -1A, $R_G \cong 6.0\Omega$, V_{GS} = -10V	
Turn-Off Delay Time (Note 11)	t _{D(off)}	_	11.2	_	ns		
Turn-Off Fall Time (Note 11)	t _f	_	5.7	_			
Total Gate Charge (Note 11)	Qg	_	2.9	_	nC	$V_{DS} = -30V, V_{GS} = -4.5V,$ $I_{D} = -0.9A$	
Total Gate Charge (Note 11)	Qg	_	5.9	_			
Gate-Source Charge (Note 11)	Q _{gs}	_	0.74	_	nC	$V_{DS} = -30V, V_{GS} = -10V,$	
Gate-Drain Charge (Note 11)	Q_{gd}	_	1.5	_		$I_D = -0.9A$	

Notes:

- 10. Measured under pulsed conditions. Pulse width = 300µs. Duty cycle ≤ 2%.
 11. Switching characteristics are independent of operating junction temperature.
 12. For design aid only, not subject to production testing.

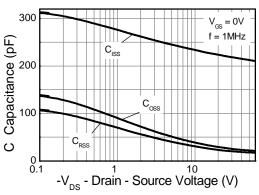


Typical Characteristics

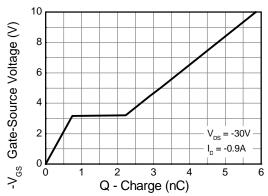




Typical Characteristics - continued

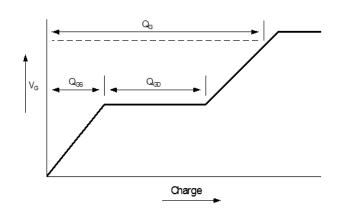


Capacitance v Drain-Source Voltage

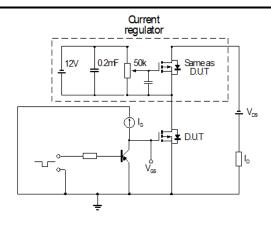


Gate-Source Voltage v Gate Charge

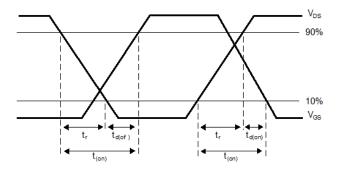
Test Circuits



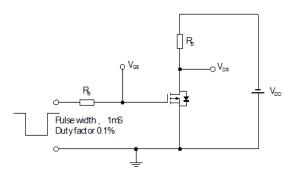
Basic gate charge waveform



Gate charge test circuit



Switching time waveforms

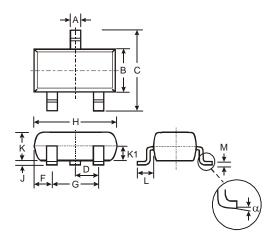


Switching time test circuit



Package Outline Dimensions

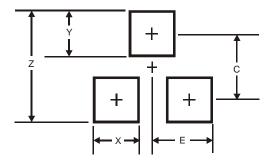
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.



SOT23						
Dim	Min	Max	Тур			
Α	0.37	0.51	0.40			
В	1.20	1.40	1.30			
С	2.30	2.50	2.40			
D	0.89	1.03	0.915			
F	0.45	0.60	0.535			
G	1.78	2.05	1.83			
Н	2.80	3.00	2.90			
J	0.013	0.10	0.05			
K	0.903	1.10	1.00			
K1	-	1	0.400			
L	0.45	0.61	0.55			
М	0.085	0.18	0.11			
α	0°	8°	-			
All Dimensions in mm						

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)		
Z	2.9		
Х	0.8		
Y	0.9		
С	2.0		
Е	1.35		





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